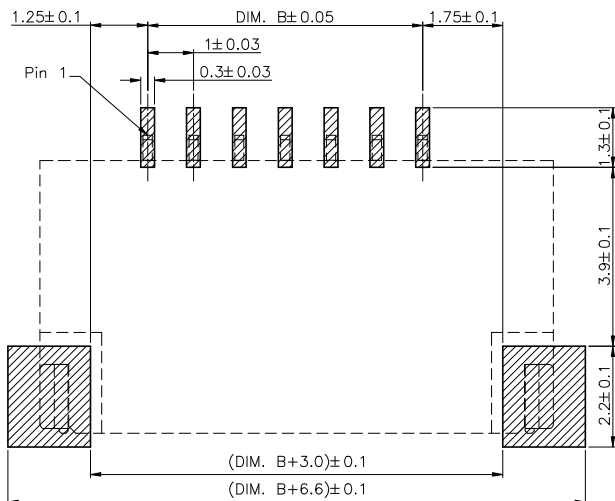
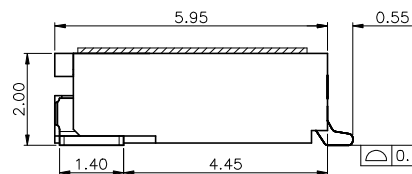
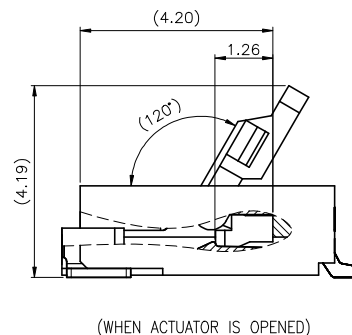
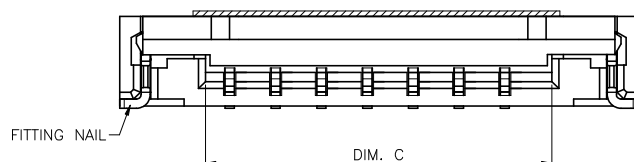
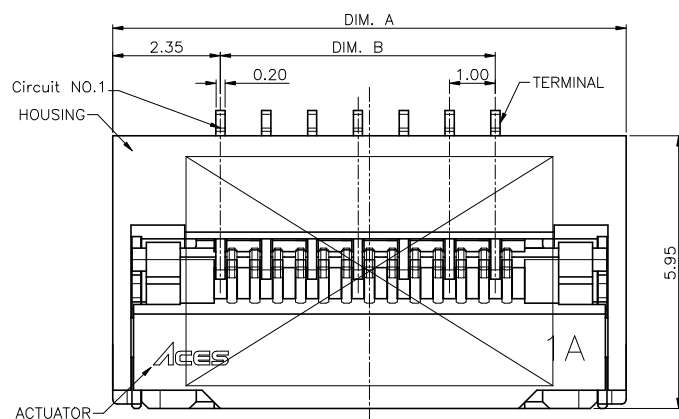
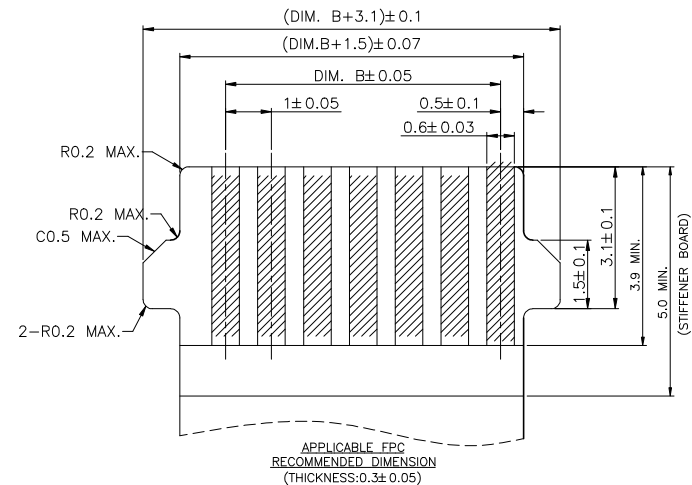




RECOMMENDED PCB LAYOUT
(TOP VIEW)



CKT	DIM A	DIM B	DIM C
25	29.30	24.00	25.56
30	34.30	29.00	30.56



NOTES:

- MATERIAL:
 - HOUSING: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:NATURAL.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - ACTUATOR: THERMOPLASTIC, HIGH TEMP.,UL94V-0; COLOR:BLACK.
- FINISH:
 - CONTACT:
 - 50~100u" NICKEL UNDERPLATING OVERALL.
 - GOLD FLASH PLATING.
 - 3u" GOLD ON CONTACT AND SOLDER FOR GOLD FLASH PLATING
 - 50~100u" NICKEL OVERALL.
 - 100~150u" MATT TIN PLATING(LEAD-FREE)
 - 15u" GOLD ON CONTACT AND SOLDER FOR GOLD FLASH PLATING
 - 15u" GOLD ON CONTACT AREA AND 1u" GOLD ON SOLDER TAIL.
- FITTING NAIL:
 - 100~150u" TIN PLATING ON SOLDER TAILS.
 - 50~100u" NICKEL UNDERPLATING OVERALL.
- REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
- SPEC. PLS. REFER TO PS-50523-XXXX
- PACKAGE PLS. REFER TO 91509-XXXX-TRP
- PART NUMBER

50692-XXX X X-001
NO OF CKT PLATING
1: G/F OVERALL(LEAD FREE)
A: 3u" GOLD ON CONTACT AND SOLDER FOR GOLD FLASH PLATING
N: MATT TIN(LEAD FREE)
4:TAPE & REEL WITH MYLAR C: 15u" GOLD ON CONTACT AND SOLDER FOR GOLD FLASH PLATING
5:TUBE WITH MYLAR S: 15u" GOLD ON CONTACT AND SOLDER FOR 1u" GOLD PLATING ON SOLDER TAIL

QUALITY SYMBOLS		DRAWN BY		DATE		ACES ELECTRONICS	
MAJOR 		Xu,Bin		22/11/28			
CRITICAL 		CHECKED BY		DATE		TITLE	
GENERAL TOLERANCES (UNLESS SPECIFIED)		Xu,Zhi Yong		22/11/28			
		APPROVED BY		DATE			
		Xu,Zhi Yong		22/11/28			
X. ±0.5		UNITS		SIZE		RFQ NO.	
.X ±0.25		mm		A4		N/A	
.XX ±0.15				REV		DWG NO.	
.XXX ±0.1				H			
ANGLES ±2°		SCALE		SHEET NO.			
		8:1		1 OF 1		50692-XXXXX-001	